

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Philippe Renaud</td> <td>08/04/2006</td> </tr> <tr> <td>Ramamurthy Ramprasad</td> <td>08/22/2006</td> </tr> </tbody> </table>		Name	Execution Date	Philippe Renaud	08/04/2006	Ramamurthy Ramprasad	08/22/2006
Name	Execution Date						
Philippe Renaud	08/04/2006						
Ramamurthy Ramprasad	08/22/2006						
RECEIVING PARTY DATA							
Name:	Freescall Semiconductor, Inc.						
Street Address:	6501 William Cannon West						
Internal Address:	Law Dept.						
City:	Austin						
State/Country:	TEXAS						
Postal Code:	78735						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10596044</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10596044		
Property Type	Number						
Application Number:	10596044						
CORRESPONDENCE DATA							
Fax Number:	(512)996-6853						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
Phone:	512-996-6839						
Email:	stacie.herrera@freescall.com						
Correspondent Name:	Freescall Semiconductor, Inc.						
Address Line 1:	7700 W. Parmer Lane						
Address Line 2:	TX32/PL02						
Address Line 4:	Austin, TEXAS 78729						
ATTORNEY DOCKET NUMBER:	SC12677ET						
NAME OF SUBMITTER:	Stacie Herrera						

Total Attachments: 3
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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **PHILIPPE RENAUD, TOURNEFEUILLE, FRANCE; and RAMAMURTHY RAMPRASAD, PHOENIX, ARIZONA** have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **HIGH FREQUENCY THIN FILM ELECTRICAL CIRCUIT ELEMENT** (Docket No. **SC12677ET**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

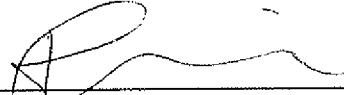
We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.



PHILIPPE RENAUD

DATE: 08/04/2006

First Witness




SIGNATURE OF WITNESS

DATE: 08/04/2006
(Month-Day-Year)

Philippe GORISSE

PRINTED NAME OF WITNESS

Second Witness



SIGNATURE OF WITNESS

DATE: 08/04/2006
(Month-Day-Year)

Amancy GENDRON

PRINTED NAME OF WITNESS

B. Ramprasad
RAMAMURTHY RAMPRASAD

DATE: 8/22/06

First Witness

Bryan D. Huey
SIGNATURE OF WITNESS

DATE: 8/22/06
(Month-Day-Year)

Bryan D. Huey
PRINTED NAME OF WITNESS

Second Witness

S.A. Boggs
SIGNATURE OF WITNESS

DATE: 22 August 2006
(Month-Day-Year)

Steven A. Boggs
PRINTED NAME OF WITNESS